

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (Withdrawn) A film carrier tape for mounting electronic devices thereon which comprises an insulating film and a wiring pattern formed thereon at least a part of which is plated with a tin-bismuth alloy deposit,

wherein a bismuth content in the tin-bismuth alloy deposit formed by plating is substantially uniform along a thickness direction thereof.

2. (Withdrawn) The film carrier tape for mounting electronic devices thereon according to claim 1, wherein said tin-bismuth alloy deposit is formed on a tin deposit formed on said wiring pattern by plating.

3. (Currently Amended) A production method of a film carrier tape for mounting electronic devices thereon which comprises:

plating at least a part of a wiring pattern formed on an insulating film with a tin-bismuth alloy plating solution in a plating tank, with the insulating film being stood up with one edge down; and

ejection washing a portion the portion of the wiring pattern plated with the tin-bismuth alloy to remove the plating solution from the wiring pattern within 6 seconds after the plating is completed stood-up film carrier tape exits the plating tank through a slit outlet opening by ejecting water from a washing nozzle; and subsequently

moving the film carrier tape to a washing tank to further wash the film carrier tape.

4. (Currently Amended) The production method according to claim 3, wherein the plating is conducted by contacting at least a part of the stood-up film carrier tape with a plating solution for forming a tin-bismuth alloy

deposit in the plating tank to form a tin-bismuth alloy deposit on at least a part of the wiring pattern.

5. (Withdrawn) A plating apparatus for a film carrier tape for mounting electronic devices thereon, said plating apparatus comprising a plating tank, a slit inlet opening through which the film carrier tape successively enters the plating tank, a slit outlet opening through which the film carrier tape exits the plating tank, and a washing nozzle for washing the film carrier tape which has exited the plating tank through the slit outlet opening.

6. (Withdrawn) The plating apparatus according to claim 5, wherein said washing nozzle is positioned between said plating tank and a washing tank provided for washing the film carrier tape.

7. (Withdrawn) The plating apparatus according to claim 5, which includes at least two washing nozzles provided in connection with a flexible tube.

8. (New) The production method according to claim 3, wherein the water is ejected from the washing nozzle along the traveling direction of the film carrier tape, and the film carrier tape moves between receivers which extend aside from both surfaces of the film carrier tape in a parallel direction and are provided at a downstream point of the washing nozzle with respect to a traveling direction of the film carrier tape.

9. (New) The production method according to claim 4, wherein the water is ejected from the washing nozzle along the traveling direction of the film carrier tape, and the film carrier tape moves between receivers which extend aside from both surfaces of the film carrier tape in a parallel direction and are provided at a downstream point of the washing nozzle with respect to a traveling direction of the film carrier tape.